



Material Content Data Sheet



Sales Product Name		BSF030NE2LQ		Issued		20. July 2018			
MA#		MA000863366							
Package		MG-WDSO-N-2-3		Weight*		48.25 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.664	3.45	3.45	34478	34478	
leadframe	non noble metal	copper	7440-50-8	45.114	93.49	93.49	934974	934974	
leadfinish	non noble metal	nickel	7440-02-0	0.115	0.24		2377		
	noble metal	silver	7440-22-4	0.456	0.95	1.19	9454	11831	
plating	non noble metal	nickel	7440-02-0	0.077	0.16	0.16	1605	1605	
glue	plastics	epoxy resin	-	0.103	0.21		2130		
	noble metal	silver	7440-22-4	0.631	1.31	1.52	13084	15214	
passivation	plastics	epoxy resin	-	0.092	0.19	0.19	1898	1898	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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